

## Features

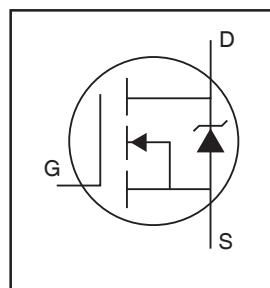
- Advanced Process Technology
- Ultra Low On-Resistance
- 175°C Operating Temperature
- Fast Switching
- Repetitive Avalanche Allowed up to  $T_{jmax}$
- Lead-Free, RoHS Compliant
- Automotive Qualified \*

## Description

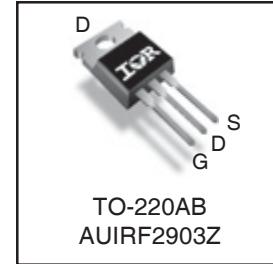
Specifically designed for Automotive applications, this HEXFET® Power MOSFET utilizes the latest processing techniques to achieve extremely low on-resistance per silicon area. Additional features of this design are a 175°C junction operating temperature, fast switching speed and improved repetitive avalanche rating. These features combine to make this design an extremely efficient and reliable device for use in Automotive applications and a wide variety of other applications.

## Absolute Maximum Ratings

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only; and functional operation of the device at these or any other condition beyond those indicated in the specifications is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions. Ambient temperature ( $T_A$ ) is 25°C, unless otherwise specified.



$V_{(BR)DSS}$	30V
$R_{DS(on)}$ typ.	1.9mΩ
	max. 2.4mΩ
$I_D$ (Silicon Limited)	260A <sup>⑨</sup>
$I_D$ (Package Limited)	160A



G	D	S
Gate	Drain	Source

	Parameter	Max.	Units
$I_D$ @ $T_C = 25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{V}$ (Silicon Limited)	260 <sup>⑨</sup>	A
$I_D$ @ $T_C = 100^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{V}$ (Silicon Limited)	180 <sup>⑨</sup>	
$I_D$ @ $T_C = 25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{V}$ (Package Limited)	160 <sup>⑨</sup>	
$I_{DM}$	Pulsed Drain Current <sup>①</sup>	1020	
$P_D @ T_C = 25^\circ\text{C}$	Power Dissipation	290	W
	Linear Derating Factor	2.0	W/°C
$V_{GS}$	Gate-to-Source Voltage	± 20	V
$E_{AS}$	Single Pulse Avalanche Energy (Thermally limited) <sup>②</sup>	290	mJ
$E_{AS}$ (Tested)	Single Pulse Avalanche Energy Tested Value <sup>⑥</sup>	820	
$I_{AR}$	Avalanche Current <sup>①</sup>	See Fig.12a, 12b, 15, 16	A
$E_{AR}$	Repetitive Avalanche Energy <sup>⑤</sup>		mJ
$T_J$	Operating Junction and	-55 to + 175	°C
$T_{STG}$	Storage Temperature Range		
	Soldering Temperature, for 10 seconds		
	Mounting Torque, 6-32 or M3 screw <sup>⑦</sup>	10 lbf*in (1.1N*m)	

## Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{θJC}$	Junction-to-Case <sup>⑧</sup>	—	0.51	°C/W
$R_{θCS}$	Case-to-Sink, Flat, Greased Surface <sup>⑦</sup>	0.50	—	
$R_{θJA}$	Junction-to-Ambient <sup>⑦</sup>	—	62	

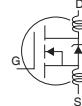
HEXFET® is a registered trademark of International Rectifier.

\*Qualification standards can be found at <http://www.irf.com/>

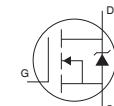
Static Electrical Characteristics @  $T_J = 25^\circ\text{C}$  (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	30	—	—	V	$V_{GS} = 0V, I_D = 250\mu\text{A}$
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	0.021	—	V/ $^\circ\text{C}$	Reference to $25^\circ\text{C}$ , $I_D = 1\text{mA}$
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	1.9	2.4	$\text{m}\Omega$	$V_{GS} = 10V, I_D = 75\text{A}$ ③**
$V_{GS(th)}$	Gate Threshold Voltage	2.0	—	4.0	V	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$
$g_{fs}$	Forward Transconductance	120	—	—	S	$V_{DS} = 10V, I_D = 75\text{A}^{**}$
$I_{DSS}$	Drain-to-Source Leakage Current	—	—	20	$\mu\text{A}$	$V_{DS} = 30V, V_{GS} = 0V$
		—	—	250		$V_{DS} = 30V, V_{GS} = 0V, T_J = 125^\circ\text{C}$
$I_{GSS}$	Gate-to-Source Forward Leakage	—	—	200	nA	$V_{GS} = 20V$
	Gate-to-Source Reverse Leakage	—	—	-200		$V_{GS} = -20V$

Dynamic Electrical Characteristics @  $T_J = 25^\circ\text{C}$  (unless otherwise specified)

$Q_g$	Total Gate Charge	—	160	240	nC	$I_D = 75\text{A}^{**}$
$Q_{gs}$	Gate-to-Source Charge	—	51	—		$V_{DS} = 24V$
$Q_{gd}$	Gate-to-Drain ("Miller") Charge	—	58	—		$V_{GS} = 10V$ ③
$t_{d(on)}$	Turn-On Delay Time	—	24	—	ns	$V_{DD} = 15V$
$t_r$	Rise Time	—	100	—		$I_D = 75\text{A}^{**}$
$t_{d(off)}$	Turn-Off Delay Time	—	48	—		$R_G = 3.2\Omega$
$t_f$	Fall Time	—	37	—		$V_{GS} = 10V$ ③
$L_D$	Internal Drain Inductance	—	4.5	—	nH	Between lead, 6mm (0.25in.) from package and center of die contact
$L_S$	Internal Source Inductance	—	7.5	—		
$C_{iss}$	Input Capacitance	—	6320	—	pF	$V_{GS} = 0V$
$C_{oss}$	Output Capacitance	—	1980	—		$V_{DS} = 25V$
$C_{rss}$	Reverse Transfer Capacitance	—	1100	—		$f = 1.0\text{MHz}$
$C_{oss}$	Output Capacitance	—	5930	—		$V_{GS} = 0V, V_{DS} = 1.0V, f = 1.0\text{MHz}$
$C_{oss}$	Output Capacitance	—	2010	—		$V_{GS} = 0V, V_{DS} = 24V, f = 1.0\text{MHz}$
$C_{oss\ eff.}$	Effective Output Capacitance	—	3050	—		$V_{GS} = 0V, V_{DS} = 0V \text{ to } 24V$ ④

## Diode Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
$I_S$	Continuous Source Current (Body Diode)	—	—	160⑨	A	MOSFET symbol showing the integral reverse p-n junction diode.
	Pulsed Source Current (Body Diode) ①	—	—	1020		
$V_{SD}$	Diode Forward Voltage	—	—	1.3	V	$T_J = 25^\circ\text{C}, I_S = 75\text{A}^{**}, V_{GS} = 0V$ ③
$t_{rr}$	Reverse Recovery Time	—	34	51	ns	$T_J = 25^\circ\text{C}, I_F = 75\text{A}^{**}, V_{DD} = 15V$
	Reverse Recovery Charge	—	29	44		$\text{di}/\text{dt} = 100\text{A}/\mu\text{s}$ ③
$t_{on}$	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

## Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature. (See fig. 11).
- ② Limited by  $T_{Jmax}$ , starting  $T_J = 25^\circ\text{C}$ ,  $L = 0.10\text{mH}$   $R_G = 25\Omega$ ,  $I_{AS} = 75\text{A}$ ,  $V_{GS} = 10V$ . Part not recommended for use above this value.
- ③ Pulse width  $\leq 1.0\text{ms}$ ; duty cycle  $\leq 2\%$ .
- ④  $C_{oss\ eff.}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 to 80%  $V_{DSS}$ .

- ⑤ Limited by  $T_{Jmax}$ , see Fig.12a, 12b, 15, 16 for typical repetitive avalanche performance.
- ⑥ This value determined from sample failure population. 100% tested to this value in production.
- ⑦ This is only applied to TO-220AB package.
- ⑧  $R_\theta$  is measured at  $T_J$  approximately  $90^\circ\text{C}$
- ⑨ Calculated continuous current based on maximum allowable junction temperature. Bond wire current limit is 160A. Note that current limitations arising from heating of the device leads may occur with some lead mounting arrangements.

\*\* All AC and DC test condition based on former Package limited current of 75A.

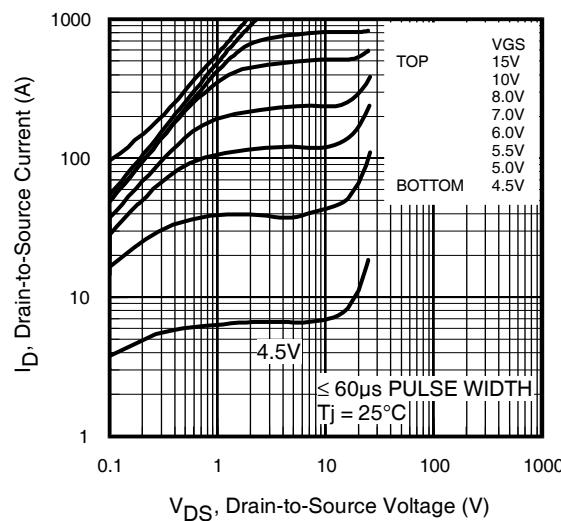
**Qualification Information<sup>†</sup>**

<b>Qualification Level</b>		Automotive (per AEC-Q101) <sup>††</sup>
		Comments: This part number(s) passed Automotive qualification. IR's Industrial and Consumer qualification level is granted by extension of the higher Automotive level.
<b>Moisture Sensitivity Level</b>		3L-TO-220      N/A
<b>ESD</b>	Machine Model	Class M4(+/- 800V) <sup>†††</sup> (per AEC-Q101-002)
	Human Body Model	Class H2(+/- 4000V) <sup>†††</sup> (per AEC-Q101-001)
	Charged Device Model	Class C5(+/- 2000V) <sup>†††</sup> (per AEC-Q101-005)
<b>RoHS Compliant</b>		Yes

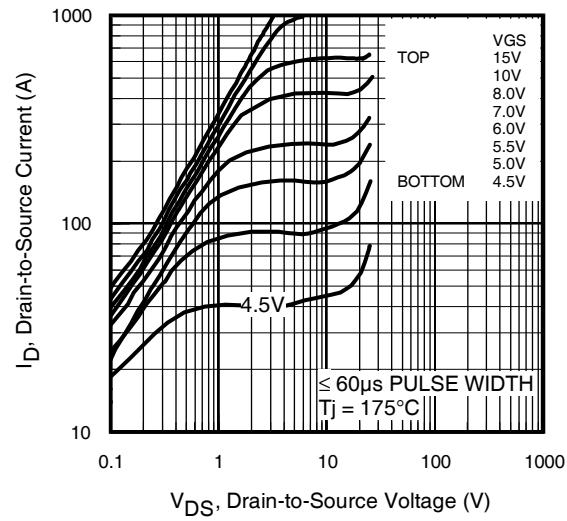
<sup>†</sup> Qualification standards can be found at International Rectifier's web site: <http://www.irf.com/>

<sup>††</sup> Exceptions to AEC-Q101 requirements are noted in the qualification report.

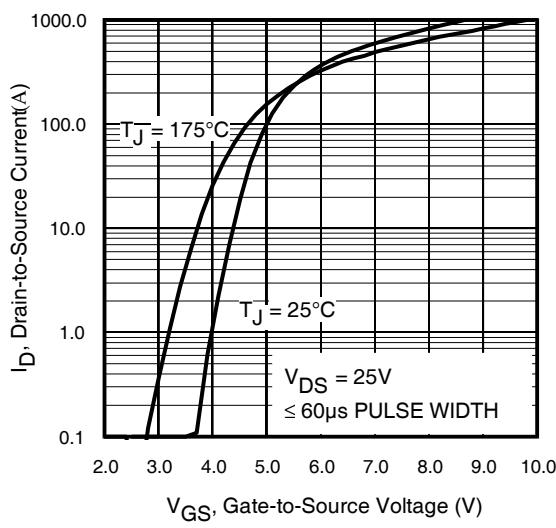
<sup>†††</sup> Highest passing voltage



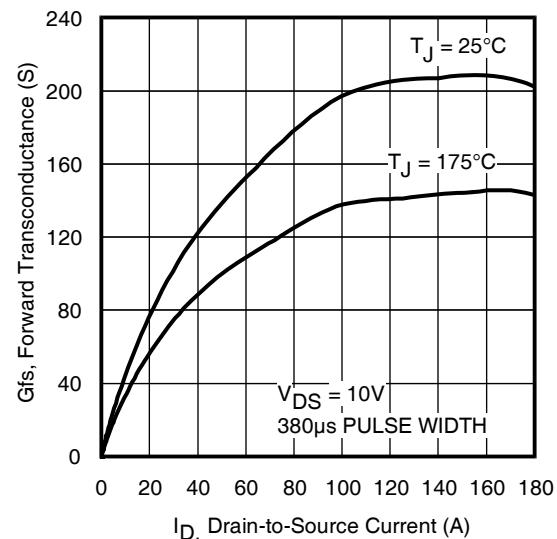
**Fig 1.** Typical Output Characteristics



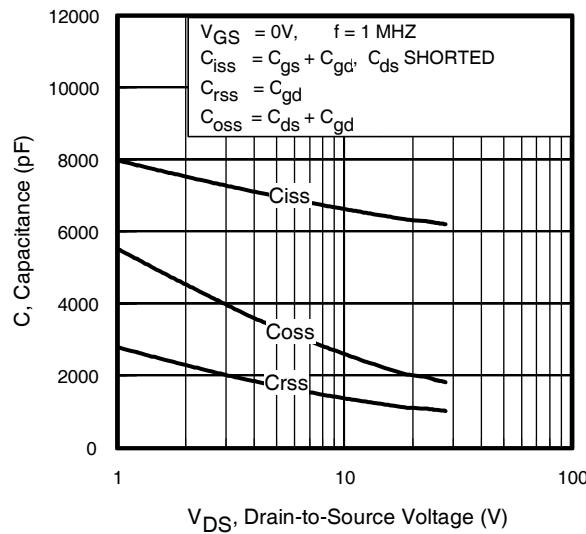
**Fig 2.** Typical Output Characteristics



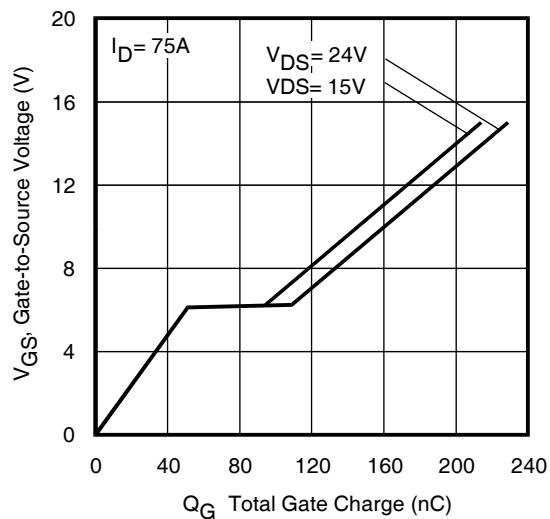
**Fig 3.** Typical Transfer Characteristics



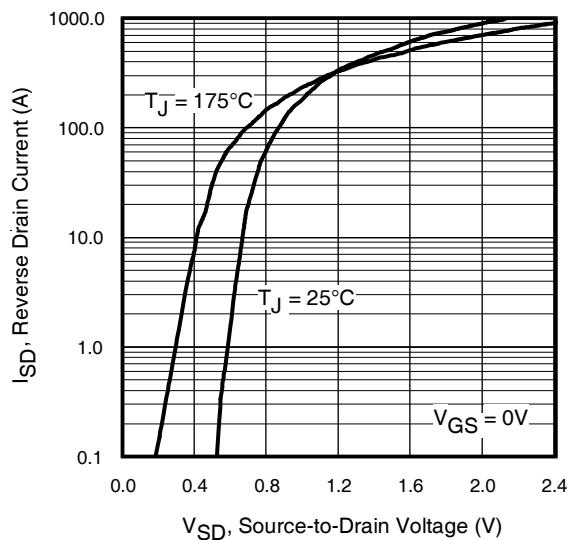
**Fig 4.** Typical Forward Transconductance Vs. Drain Current



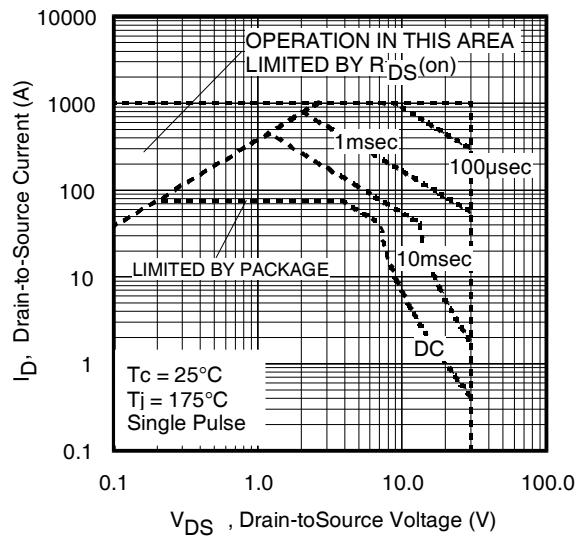
**Fig 5.** Typical Capacitance Vs.  
Drain-to-Source Voltage



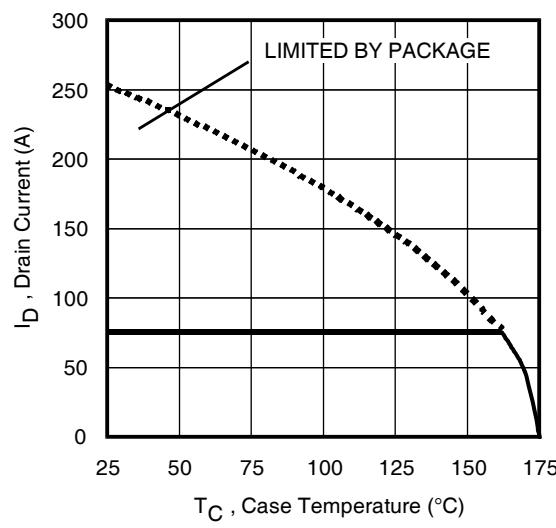
**Fig 6.** Typical Gate Charge Vs.  
Gate-to-Source Voltage



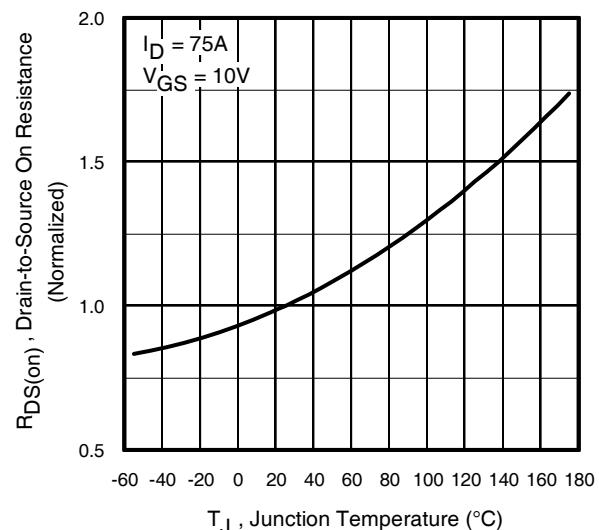
**Fig 7.** Typical Source-Drain Diode  
Forward Voltage



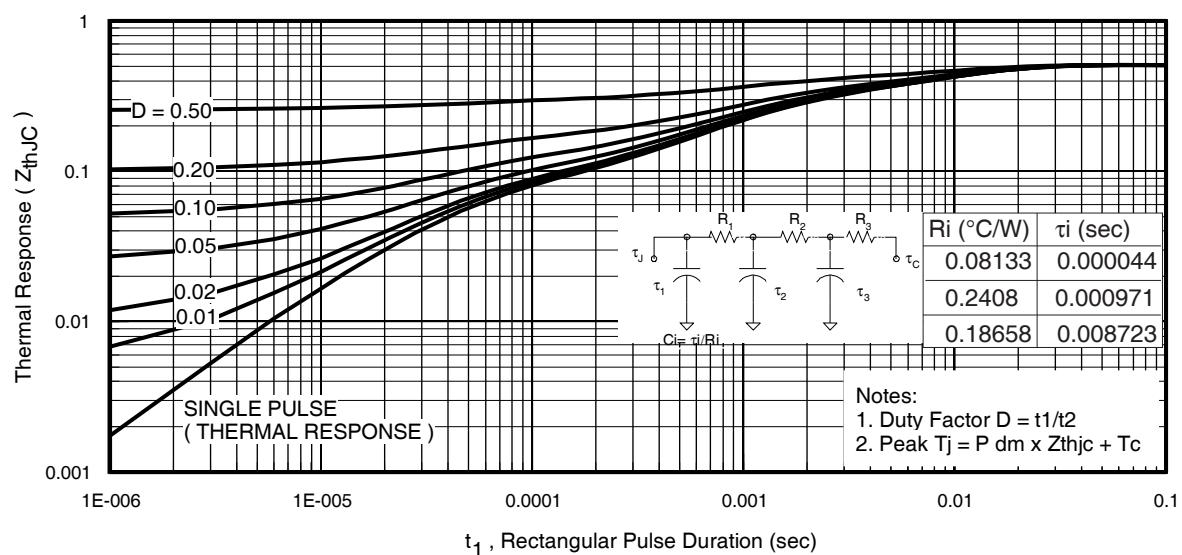
**Fig 8.** Maximum Safe Operating Area



**Fig 9.** Maximum Drain Current Vs.  
Case Temperature



**Fig 10.** Normalized On-Resistance  
Vs. Temperature



**Fig 11.** Maximum Effective Transient Thermal Impedance, Junction-to-Case

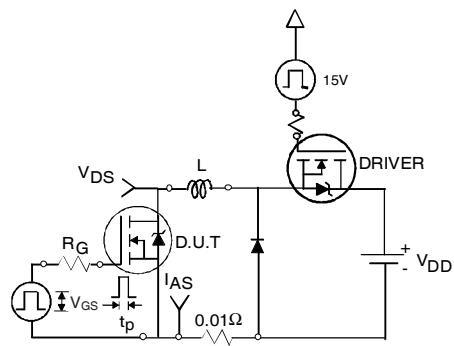


Fig 12a. Unclamped Inductive Test Circuit

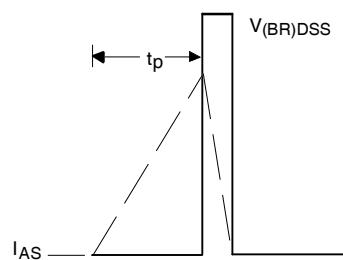


Fig 12b. Unclamped Inductive Waveforms

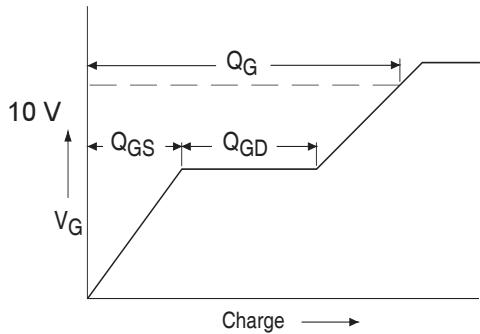


Fig 13a. Basic Gate Charge Waveform

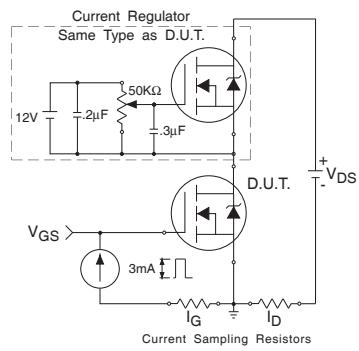


Fig 13b. Gate Charge Test Circuit

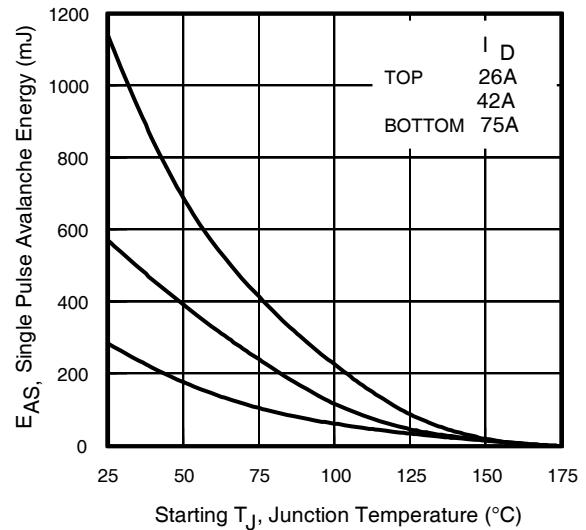


Fig 12c. Maximum Avalanche Energy Vs. Drain Current

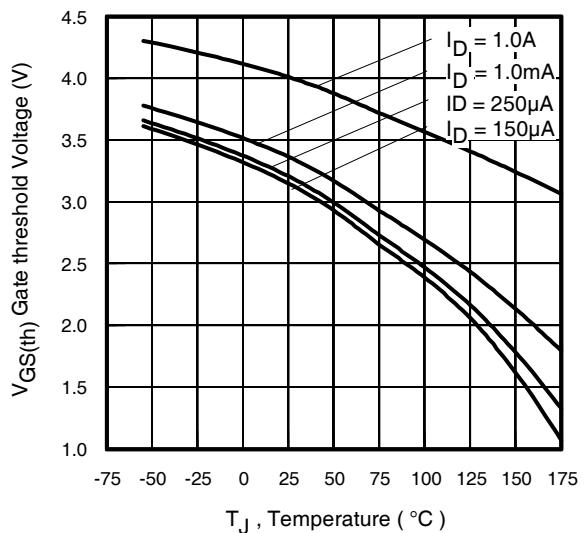


Fig 14. Threshold Voltage Vs. Temperature

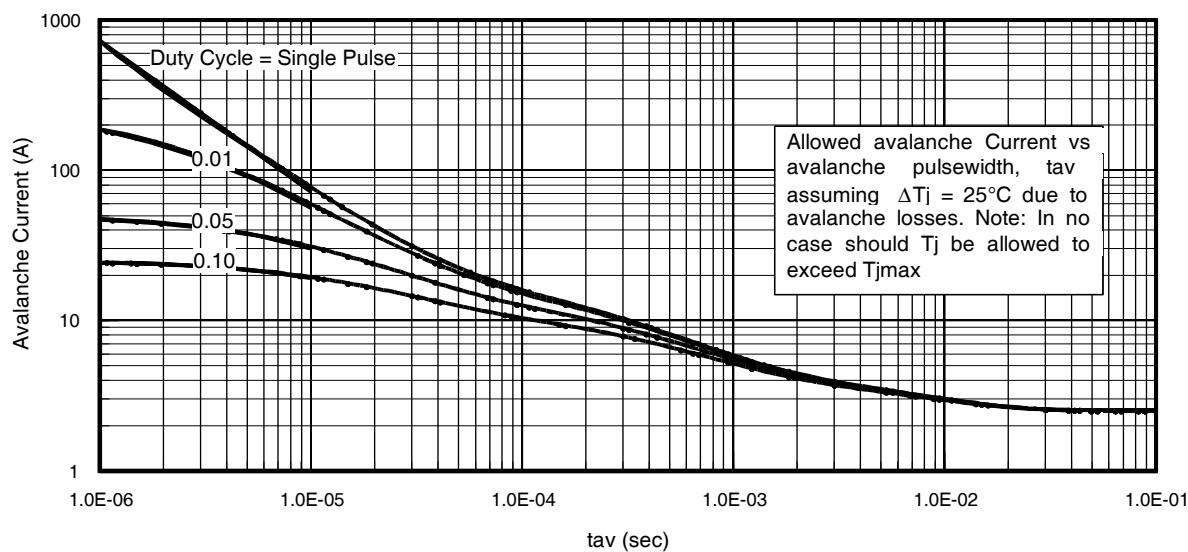


Fig 15. Typical Avalanche Current Vs.Pulsewidth

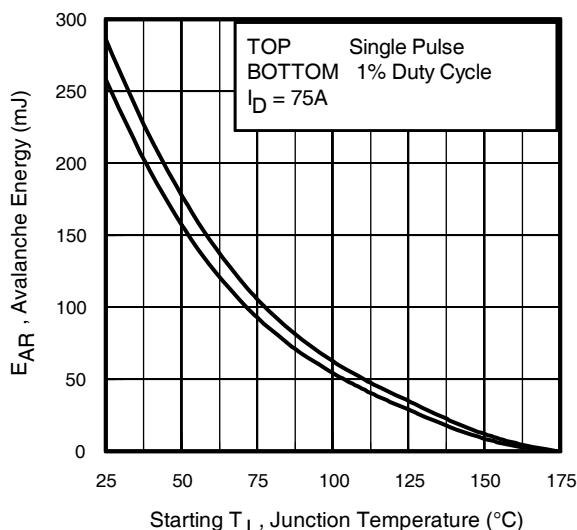


Fig 16. Maximum Avalanche Energy Vs. Temperature

Notes on Repetitive Avalanche Curves , Figures 15, 16:  
(For further info, see AN-1005 at [www.irf.com](http://www.irf.com))

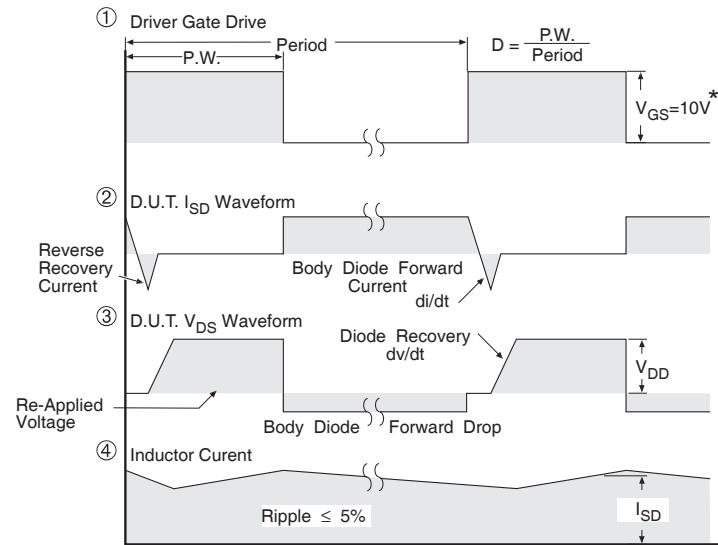
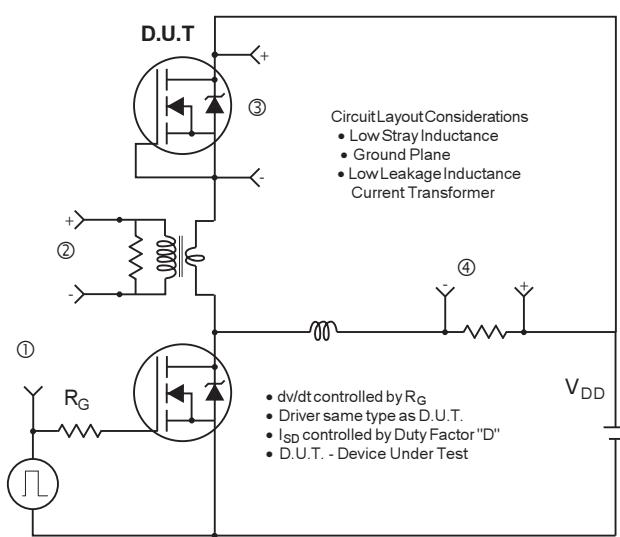
1. Avalanche failures assumption:  
Purely a thermal phenomenon and failure occurs at a temperature far in excess of T<sub>jmax</sub>. This is validated for every part type.
2. Safe operation in Avalanche is allowed as long as T<sub>jmax</sub> is not exceeded.
3. Equation below based on circuit and waveforms shown in Figures 12a, 12b.
4. P<sub>D (ave)</sub> = Average power dissipation per single avalanche pulse.
5. BV = Rated breakdown voltage (1.3 factor accounts for voltage increase during avalanche).
6. I<sub>av</sub> = Allowable avalanche current.
7.  $\Delta T$  = Allowable rise in junction temperature, not to exceed T<sub>jmax</sub> (assumed as 25°C in Figure 15, 16).

t<sub>av</sub> = Average time in avalanche.  
D = Duty cycle in avalanche = t<sub>av</sub> · f  
Z<sub>thJC</sub>(D, t<sub>av</sub>) = Transient thermal resistance, see figure 11)

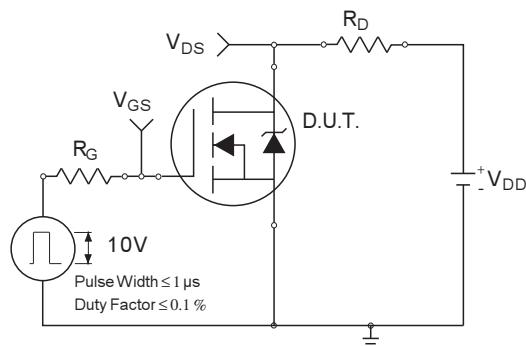
$$P_{D \text{ (ave)}} = 1/2 (1.3 \cdot BV \cdot I_{av}) = \Delta T / Z_{thJC}$$

$$I_{av} = 2 \Delta T / [1.3 \cdot BV \cdot Z_{th}]$$

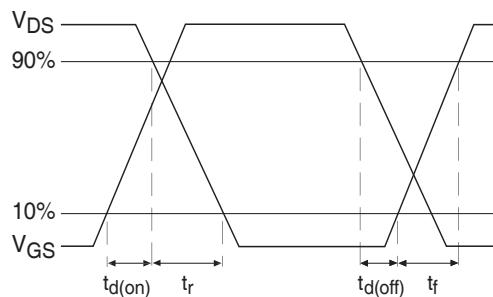
$$E_{AS \text{ (AR)}} = P_{D \text{ (ave)}} \cdot t_{av}$$



**Fig 17.** Peak Diode Recovery  $dv/dt$  Test Circuit for N-Channel HEXFET® Power MOSFETs



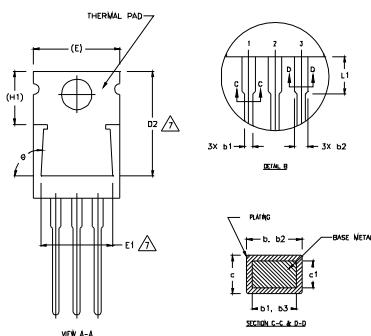
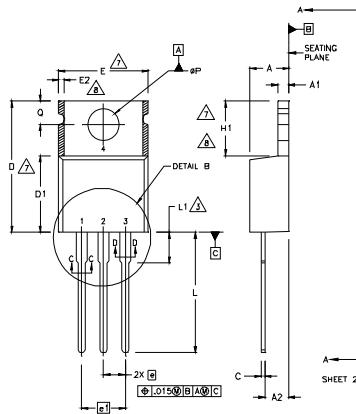
**Fig 18a.** Switching Time Test Circuit



**Fig 18b.** Switching Time Waveforms

## TO-220AB Package Outline

Dimensions are shown in millimeters (inches)



## NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5 M- 1994.
2. DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS].
3. LEAD DIMENSION AND FINISH UNCONTROLLED IN L1.
4. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .005" (0.127) PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
5. DIMENSION b1 & c1 APPLY TO BASE METAL ONLY.
6. CONTROLLING DIMENSION : INCHES.
7. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS E,H1,D2 & E1
8. DIMENSION E2 X H1 DEFINE A ZONE WHERE STAMPING AND SINGULATION IRREGULARITIES ARE ALLOWED.

## LEAD ASSIGNMENTS

## HEXFET

- 1.- GATE
- 2.- DRAIN
- 3.- SOURCE

## IGBTs, CoPACK

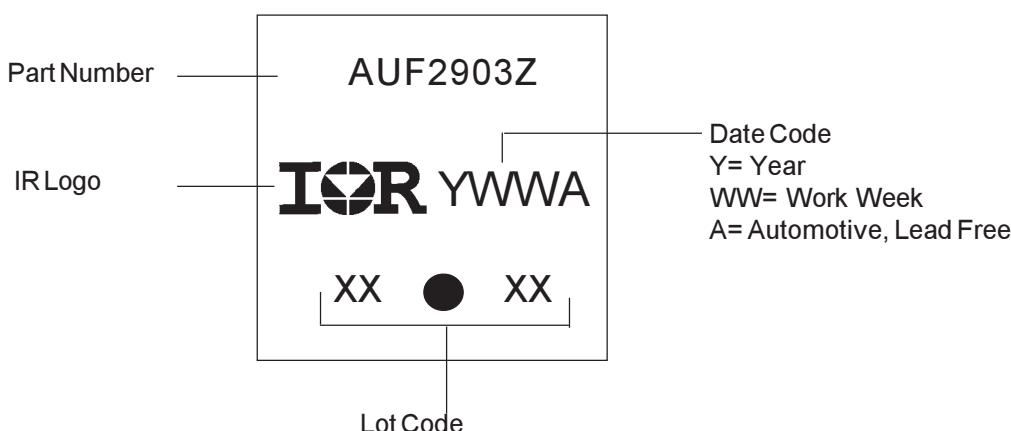
- 1.- GATE
- 2.- COLLECTOR
- 3.- Emitter

## DIODES

- 1.- ANODE/OPEN
- 2.- CATHODE
- 3.- ANODE

SYMBOL	DIMENSIONS				NOTES	
	MILLIMETERS		INCHES			
	MIN.	MAX.	MIN.	MAX.		
A	3.56	4.82	.140	.190		
A1	0.51	1.40	.020	.055		
A2	2.04	2.92	.080	.115		
b	0.38	1.01	.015	.040		
b1	0.38	0.96	.015	.038	5	
b2	1.15	1.77	.045	.070		
b3	1.15	1.73	.045	.068		
c	0.36	0.61	.014	.024		
c1	0.36	0.56	.014	.022	5	
D	14.22	16.51	.560	.650	4	
D1	8.38	9.02	.330	.355		
D2	12.19	12.88	.480	.507	7	
E	9.66	10.66	.380	.420	4,7	
E1	8.38	8.89	.330	.350	7	
e	2.54	BSC	.100	BSC		
e1	5.08		.200	BSC		
H1	5.85	6.55	.230	.270	7,8	
L	12.70	14.73	.500	.580		
L1	—	6.35	—	.250		
ØP	3.54	4.08	.139	.161		
Q	2.54	3.42	.100	.135		
Ø	90°-93°		90°-93°			

## TO-220AB Part Marking Information

Note: For the most current drawing please refer to IR website at <http://www.irf.com/package/>

**Ordering Information**

Base part	Package Type	Standard Pack		Complete Part Number
		Form	Quantity	
AUIRF2903Z	TO-220	Tube	50	AUIRF2903Z

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For technical support, please contact IR's Technical Assistance Center  
<http://www.irf.com/technical-info/>

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